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|---|---|--|---------------------------|----------------------|--------------------------------|----------------------|-------------------------------------|----------------------|---|
| Form Type | Distribute | Version | 2.0 | Ref | IPC 1752A | Sectionals | Material Info | Subsectionals | D, A |
| Supplier Information | | | | | | | | | |
| Company Name | TE Connectivity | Request Document ID | | Contact Name | Benfer David W | Contact Title | Product Compliance Engineer for DND | | |
| Company Unique ID | TE Connectivity | Response Date | 2017-02-02 | Contact Email | dave.benfer@te.com | | | | |
| Contact Phone Number | 717-986-3725 | | | | | | | | |
| Legal Statement | | | | | | | | | |
| Supplier Acceptance | true | | | | | | | | |
| Legal Statement | | | | | | | | | |
| The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers. | | | | | | | | | |
| Product | | | | | | | | | |
| Manufacturer Item number | 1-1337526-0 | Amount | 24520.53 | Version | - | Identity | | | |
| Manufacturer Item Name | BNC R/A Adp PJ 75Ohm Nickel Pltd | Weight Uom | mg | Mfr Site | | Authority | | | |
| Date | | UOM | Each | | | | | | |
| EURoHS-0508 | Product(s) meets EU RoHS requirements by application of the selected exemption(s) | | | | | | | | |
| ChinaRoHS-0508 | Product(s) is NOT eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products | | | | | | | | |
| EUREACH-1215 | REACH Candidate Substances of Very High Concern ARE NOT Contained in the Product Above the Limits per the Definition within REACH | | | | | | | | |
| Product Disclosure | | | | | | | | | |
| Sub-Item/Material/Substance | Level | Name | Substance Category | Substance CAS | Substance Concentration | Quantity | Mass per Unit | UOM | Exemption |
| Material | 1 | CONTACT PIN-Gold Plating | | | | 1.0 | 1.89 | mg | |
| Substance | 2 | Gold | Supplier | 7440-57-5 | 99.7 | 1.0 | 1.88433 | mg | |
| Substance | 2 | Contains No Reportable TE5081-2 Substances | Supplier | TE5081-2-1212 | 0.3 | 1.0 | 0.00567 | mg | |
| Material | 1 | RETAIN RING | | | | 1.0 | 160.0 | mg | |
| Substance | 2 | Zinc | Supplier | 7440-66-6 | 38.127 | 1.0 | 61.0032 | mg | |
| Substance | 2 | Tin | Supplier | 7440-31-5 | 0.272 | 1.0 | 0.4352 | mg | |
| Substance | 2 | Copper | Supplier | 7440-50-8 | 58.463 | 1.0 | 93.5408 | mg | |
| Substance | 2 | Iron | Supplier | 7439-89-6 | 0.273 | 1.0 | 0.4368 | mg | |
| Substance | 2 | Lead | Lead/Lead Compounds | 7439-92-1 | 2.865 | 1.0 | 4.584 | mg | 6(c) Lead as an alloying element in copper containing up to 4% lead by weight |
| Material | 1 | C RING-Copper Plating | | | | 1.0 | 1.02 | mg | |
| Substance | 2 | Contains No Reportable TE5081-2 Substances | Supplier | TE5081-2-1212 | 0.01 | 1.0 | 1.02E-4 | mg | |
| Substance | 2 | Copper | Supplier | 7440-50-8 | 99.99 | 1.0 | 1.0199 | mg | |
| Material | 1 | RING | | | | 1.0 | 400.0 | mg | |
| Substance | 2 | Nickel | Nickel | 7440-02-0 | 0.12 | 1.0 | 0.48 | mg | |
| Substance | 2 | Chromium | Supplier | 7440-47-3 | 0.1 | 1.0 | 0.4 | mg | |
| Substance | 2 | Silicon | Supplier | 7440-21-3 | 0.35 | 1.0 | 1.4 | mg | |
| Substance | 2 | Phosphorus | Supplier | 7723-14-0 | 0.03 | 1.0 | 0.12 | mg | |
| Substance | 2 | Sulfur | Supplier | 7704-34-9 | 0.03 | 1.0 | 0.12 | mg | |
| Substance | 2 | Carbon | Supplier | 7440-44-0 | 0.9 | 1.0 | 3.6 | mg | |
| Substance | 2 | Manganese | Supplier | 7439-96-5 | 0.5 | 1.0 | 2.0 | mg | |
| Substance | 2 | Iron | Supplier | 7439-89-6 | 97.97 | 1.0 | 391.88 | mg | |
| Material | 1 | CONTACT PIN-Nickel Plating | | | | 1.0 | 8.62 | mg | |
| Substance | 2 | Nickel | Nickel | 7440-02-0 | 99.99 | 1.0 | 8.61914 | mg | |

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|-----------|---|--|---------------------|---------------|--------|-----|-----------|----|---|
| Substance | 2 | Contains No Reportable TE5081-2 Substances | Supplier | TE5081-2-1212 | 0.01 | 1.0 | 8.62E-4 | mg | |
| Material | 1 | RETAIN RING-Nickel Plating | | | | 1.0 | 3.26 | mg | |
| Substance | 2 | Nickel | Nickel | 7440-02-0 | 99.99 | 1.0 | 3.25967 | mg | |
| Substance | 2 | Contains No Reportable TE5081-2 Substances | Supplier | TE5081-2-1212 | 0.01 | 1.0 | 3.26E-4 | mg | |
| Material | 1 | BNC ASSEMBLY-Copper Plating | | | | 1.0 | 4.22 | mg | |
| Substance | 2 | Contains No Reportable TE5081-2 Substances | Supplier | TE5081-2-1212 | 0.01 | 1.0 | 4.22E-4 | mg | |
| Substance | 2 | Copper | Supplier | 7440-50-8 | 99.99 | 1.0 | 4.21958 | mg | |
| Material | 1 | BNC ASSEMBLY | | | | 1.0 | 9440.0 | mg | |
| Substance | 2 | Lead | Lead/Lead Compounds | 7439-92-1 | 2.865 | 1.0 | 270.456 | mg | 6(c) Lead as an alloying element in copper containing up to 4% lead by weight |
| Substance | 2 | Iron | Supplier | 7439-89-6 | 0.273 | 1.0 | 25.7712 | mg | |
| Substance | 2 | Copper | Supplier | 7440-50-8 | 58.463 | 1.0 | 5518.9072 | mg | |
| Substance | 2 | Zinc | Supplier | 7440-66-6 | 38.127 | 1.0 | 3599.1888 | mg | |
| Substance | 2 | Tin | Supplier | 7440-31-5 | 0.272 | 1.0 | 25.6768 | mg | |
| Material | 1 | RETAIN RING-Copper Plating | | | | 1.0 | 3.66 | mg | |
| Substance | 2 | Copper | Supplier | 7440-50-8 | 99.99 | 1.0 | 3.65963 | mg | |
| Substance | 2 | Contains No Reportable TE5081-2 Substances | Supplier | TE5081-2-1212 | 0.01 | 1.0 | 3.66E-4 | mg | |
| Material | 1 | SPRING RING | | | | 1.0 | 200.0 | mg | |
| Substance | 2 | Nickel | Nickel | 7440-02-0 | 0.03 | 1.0 | 0.06 | mg | |
| Substance | 2 | Carbon | Supplier | 7440-44-0 | 0.71 | 1.0 | 1.42 | mg | |
| Substance | 2 | Copper | Supplier | 7440-50-8 | 0.05 | 1.0 | 0.1 | mg | |
| Substance | 2 | Chromium | Supplier | 7440-47-3 | 0.07 | 1.0 | 0.14 | mg | |
| Substance | 2 | Phosphorus | Supplier | 7723-14-0 | 0.11 | 1.0 | 0.22 | mg | |
| Substance | 2 | Silicon | Supplier | 7440-21-3 | 0.25 | 1.0 | 0.5 | mg | |
| Substance | 2 | Manganese | Supplier | 7439-96-5 | 0.58 | 1.0 | 1.16 | mg | |
| Substance | 2 | Iron | Supplier | 7439-89-6 | 98.19 | 1.0 | 196.38 | mg | |
| Substance | 2 | Sulfur | Supplier | 7704-34-9 | 0.01 | 1.0 | 0.02 | mg | |
| Material | 1 | INSULATOR | | | | 1.0 | 1762.0 | mg | |
| Substance | 2 | Ethene, 1,1,2,2-tetrafluoro-, homopolymer | Supplier | 9002-84-0 | 100.0 | 1.0 | 1762.0 | mg | |
| Material | 1 | SPRING RING-Copper Plating | | | | 1.0 | 2.62 | mg | |
| Substance | 2 | Copper | Supplier | 7440-50-8 | 99.99 | 1.0 | 2.61974 | mg | |
| Substance | 2 | Contains No Reportable TE5081-2 Substances | Supplier | TE5081-2-1212 | 0.01 | 1.0 | 2.62E-4 | mg | |
| Material | 1 | SHELL-Nickel Plating | | | | 1.0 | 25.6 | mg | |
| Substance | 2 | Nickel | Nickel | 7440-02-0 | 99.99 | 1.0 | 25.59744 | mg | |
| Substance | 2 | Contains No Reportable TE5081-2 Substances | Supplier | TE5081-2-1212 | 0.01 | 1.0 | 0.00256 | mg | |
| Material | 1 | RING-Copper Plating | | | | 1.0 | 0.65 | mg | |
| Substance | 2 | Copper | Supplier | 7440-50-8 | 99.99 | 1.0 | 0.64994 | mg | |
| Substance | 2 | Contains No Reportable TE5081-2 Substances | Supplier | TE5081-2-1212 | 0.01 | 1.0 | 6.5E-5 | mg | |
| Material | 1 | BNC ASSEMBLY-Nickel Plating | | | | 1.0 | 39.6 | mg | |
| Substance | 2 | Contains No Reportable TE5081-2 Substances | Supplier | TE5081-2-1212 | 0.01 | 1.0 | 0.00396 | mg | |
| Substance | 2 | Nickel | Nickel | 7440-02-0 | 99.99 | 1.0 | 39.59604 | mg | |
| Material | 1 | C RING-Nickel Plating | | | | 1.0 | 2.61 | mg | |

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|-----------|---|--|---------------------|---------------|--------|-----|------------|----|---|
| Substance | 2 | Nickel | Nickel | 7440-02-0 | 99.99 | 1.0 | 2.60974 | mg | |
| Substance | 2 | Contains No Reportable TE5081-2 Substances | Supplier | TE5081-2-1212 | 0.01 | 1.0 | 2.61E-4 | mg | |
| Material | 1 | SHELL-Copper Plating | | | | 1.0 | 6.23 | mg | |
| Substance | 2 | Contains No Reportable TE5081-2 Substances | Supplier | TE5081-2-1212 | 0.01 | 1.0 | 6.23E-4 | mg | |
| Substance | 2 | Copper | Supplier | 7440-50-8 | 99.99 | 1.0 | 6.22938 | mg | |
| Material | 1 | SPRING RING-Nickel Plating | | | | 1.0 | 4.68 | mg | |
| Substance | 2 | Contains No Reportable TE5081-2 Substances | Supplier | TE5081-2-1212 | 0.01 | 1.0 | 4.68E-4 | mg | |
| Substance | 2 | Nickel | Nickel | 7440-02-0 | 99.99 | 1.0 | 4.67953 | mg | |
| Material | 1 | GASKET | | | | 1.0 | 60.0 | mg | |
| Substance | 2 | Rubber, silicone | Supplier | 63394-02-5 | 100.0 | 1.0 | 60.0 | mg | |
| Material | 1 | SHELL | | | | 1.0 | 4223.0 | mg | |
| Substance | 2 | Lead | Lead/Lead Compounds | 7439-92-1 | 2.865 | 1.0 | 120.98895 | mg | 6(c) Lead as an alloying element in copper containing up to 4% lead by weight |
| Substance | 2 | Iron | Supplier | 7439-89-6 | 0.273 | 1.0 | 11.52879 | mg | |
| Substance | 2 | Tin | Supplier | 7440-31-5 | 0.272 | 1.0 | 11.48656 | mg | |
| Substance | 2 | Zinc | Supplier | 7440-66-6 | 38.127 | 1.0 | 1610.10321 | mg | |
| Substance | 2 | Copper | Supplier | 7440-50-8 | 58.463 | 1.0 | 2468.89249 | mg | |
| Material | 1 | BODY-Nickel Plating | | | | 1.0 | 32.2 | mg | |
| Substance | 2 | Contains No Reportable TE5081-2 Substances | Supplier | TE5081-2-1212 | 0.01 | 1.0 | 0.00322 | mg | |
| Substance | 2 | Nickel | Nickel | 7440-02-0 | 99.99 | 1.0 | 32.19678 | mg | |
| Material | 1 | CONTACT PIN-Copper Plating | | | | 1.0 | 1.56 | mg | |
| Substance | 2 | Copper | Supplier | 7440-50-8 | 99.99 | 1.0 | 1.55984 | mg | |
| Substance | 2 | Contains No Reportable TE5081-2 Substances | Supplier | TE5081-2-1212 | 0.01 | 1.0 | 1.56E-4 | mg | |
| Material | 1 | BODY | | | | 1.0 | 7320.0 | mg | |
| Substance | 2 | Lead | Lead/Lead Compounds | 7439-92-1 | 2.865 | 1.0 | 209.718 | mg | 6(c) Lead as an alloying element in copper containing up to 4% lead by weight |
| Substance | 2 | Iron | Supplier | 7439-89-6 | 0.273 | 1.0 | 19.9836 | mg | |
| Substance | 2 | Tin | Supplier | 7440-31-5 | 0.272 | 1.0 | 19.9104 | mg | |
| Substance | 2 | Copper | Supplier | 7440-50-8 | 58.463 | 1.0 | 4279.4916 | mg | |
| Substance | 2 | Zinc | Supplier | 7440-66-6 | 38.127 | 1.0 | 2790.8964 | mg | |
| Material | 1 | RING-Nickel Plating | | | | 1.0 | 2.85 | mg | |
| Substance | 2 | Nickel | Nickel | 7440-02-0 | 99.99 | 1.0 | 2.84971 | mg | |
| Substance | 2 | Contains No Reportable TE5081-2 Substances | Supplier | TE5081-2-1212 | 0.01 | 1.0 | 2.85E-4 | mg | |
| Material | 1 | CONTACT PIN | | | | 1.0 | 540.0 | mg | |
| Substance | 2 | Zinc | Supplier | 7440-66-6 | 3.86 | 1.0 | 20.844 | mg | |
| Substance | 2 | Iron | Supplier | 7439-89-6 | 0.07 | 1.0 | 0.378 | mg | |
| Substance | 2 | Copper | Supplier | 7440-50-8 | 88.77 | 1.0 | 479.358 | mg | |
| Substance | 2 | Phosphorus | Supplier | 7723-14-0 | 0.03 | 1.0 | 0.162 | mg | |
| Substance | 2 | Tin | Supplier | 7440-31-5 | 3.75 | 1.0 | 20.25 | mg | |
| Substance | 2 | Lead | Lead/Lead Compounds | 7439-92-1 | 3.52 | 1.0 | 19.008 | mg | 6(c) Lead as an alloying element in copper containing up to 4% lead by weight |
| Material | 1 | BODY-Copper Plating | | | | 1.0 | 6.26 | mg | |

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| Substance | 2 | Contains No Reportable TE5081-2 Substances | Supplier | TE5081-2-1212 | 0.01 | 1.0 | 6.26E-4 | mg | |
| Substance | 2 | Copper | Supplier | 7440-50-8 | 99.99 | 1.0 | 6.25937 | mg | |
| Material | 1 | C RING | | | | 1.0 | 268.0 | mg | |
| Substance | 2 | Silicon | Supplier | 7440-21-3 | 0.35 | 1.0 | 0.938 | mg | |
| Substance | 2 | Manganese | Supplier | 7439-96-5 | 0.5 | 1.0 | 1.34 | mg | |
| Substance | 2 | Carbon | Supplier | 7440-44-0 | 0.9 | 1.0 | 2.412 | mg | |
| Substance | 2 | Iron | Supplier | 7439-89-6 | 97.97 | 1.0 | 262.5596 | mg | |
| Substance | 2 | Sulfur | Supplier | 7704-34-9 | 0.03 | 1.0 | 0.0804 | mg | |
| Substance | 2 | Chromium | Supplier | 7440-47-3 | 0.1 | 1.0 | 0.268 | mg | |
| Substance | 2 | Phosphorus | Supplier | 7723-14-0 | 0.03 | 1.0 | 0.0804 | mg | |
| Substance | 2 | Nickel | Nickel | 7440-02-0 | 0.12 | 1.0 | 0.3216 | mg | |